



JCU CORPORATION

Financial Results Briefing Material

for the First Quarter of the Fiscal Year
Ending March 2025

JCU CORPORATION

TSE Prime (Stock Code: 4975)

August 7, 2024

Summary of Consolidated Financial Results for 1Q FY3/25



Accounting Period of 1Q FY3/25

JCU (non-consolidated): April 1 to June 30, 2024

Overseas subsidiaries: January 1 to March 31, 2024

Chemicals Business

For electronic components

- China: The inventory adjustment of high-performance electronic devices including smartphones ran its course, resulting in a recovery trend in the demand for PWBs. As a result, sales of chemicals substantially increased year over year.
- Taiwan: With signs of recovery in the semiconductor market, demand for servers and semiconductor package substrates for high-performance electronic devices moderately expanded. As a result, sales of chemicals increased year over year.
- South Korea: Due to the bottoming out of the semiconductor market and the progress in inventory adjustment by customers, demand for semiconductor package substrates showed a moderate recovery. As a result, sales of chemicals increased year over year.

For decoration

- Japan: Automobile production decreased due to the suspension of shipments by some automobile manufacturers, and demand for chemicals declined following the changes in design trends. As a result, sales of chemicals decreased year over year.
- China: Despite increases in automobile production due to an improvement in shortages of semiconductors and parts, demand for automobile parts which is subject to our business decreased. Sales of chemicals stayed flat year over year.

Machine Business

- Sales increased thanks to the ordered projects progressing on schedule. However, orders received decreased due to a decline in new orders for large projects.

Summary of Financial Results for 1Q FY3/25



(Millions of yen)

	Same period of previous FY (1Q FY3/24)	1Q FY3/25	YoY % Change
Net sales	5,225	5,912	13.1%
Operating profit	1,379	1,995	44.7%
Ordinary profit	1,383	2,237	61.7%
Profit attributable to owners of parent	944	1,508	59.7%
Net income per share	36.85 yen	59.55 yen	-

Foreign Exchange Rates



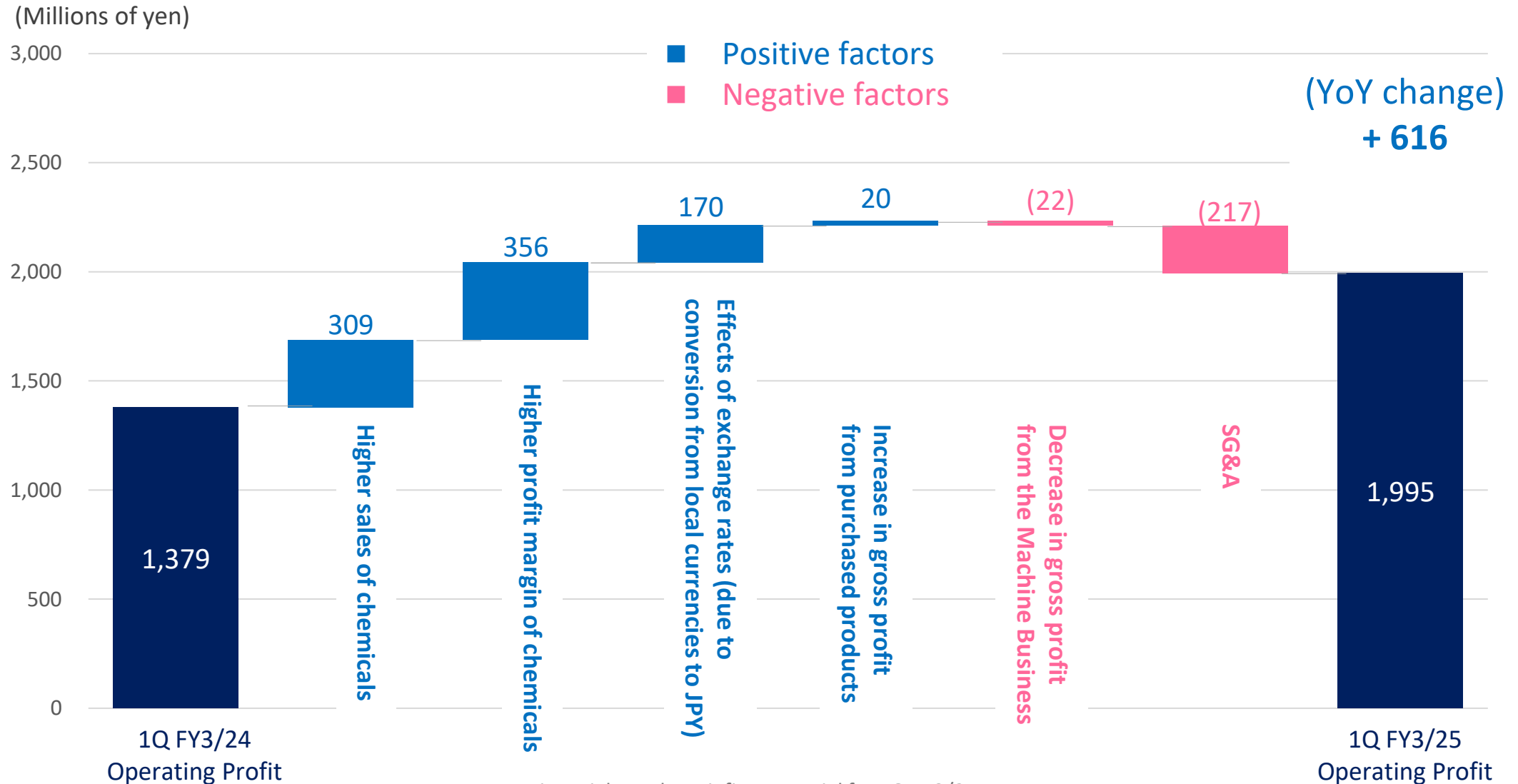
Foreign exchange sensitivity (as at the consolidated year):
Changes of about 100 million yen in consolidated operating profit with 1% change in major currency rates listed below

(Yen)

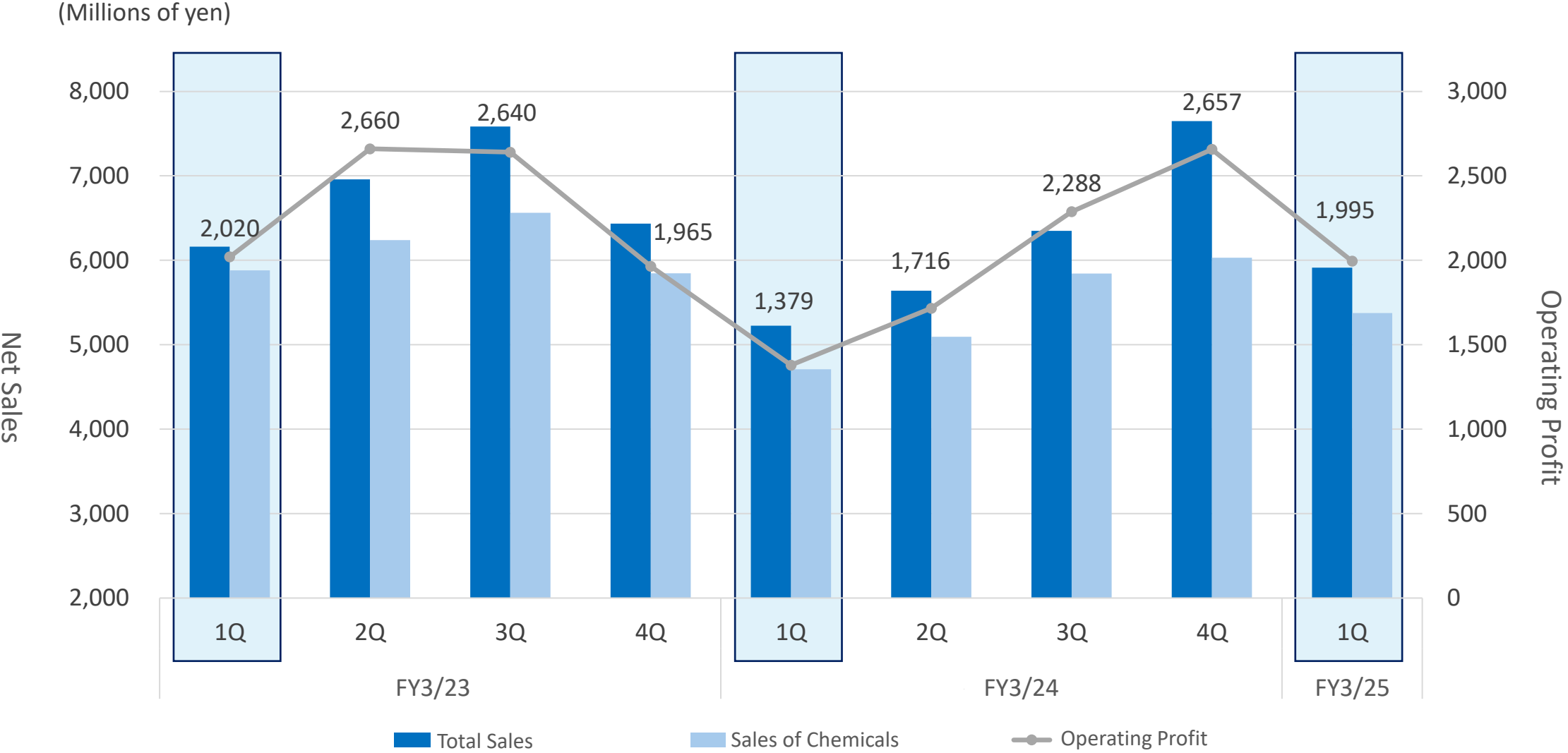
	FY3/24				FY3/25	
	1Q	2Q	3Q	4Q	(Initial forecast)	1Q
Chinese yuan (CNY)	19.34	19.45	19.61	19.82	20.40	20.63
Taiwan dollar (TWD)	4.36	4.42	4.47	4.51	4.60	4.73
Korean won (KRW)	0.1039	0.1042	0.1062	0.1076	0.1100	0.1117

Note: The average rate for the period is used to translate Chinese yuan, Taiwan dollar and Korean won, our major foreign currencies, to Japanese yen.

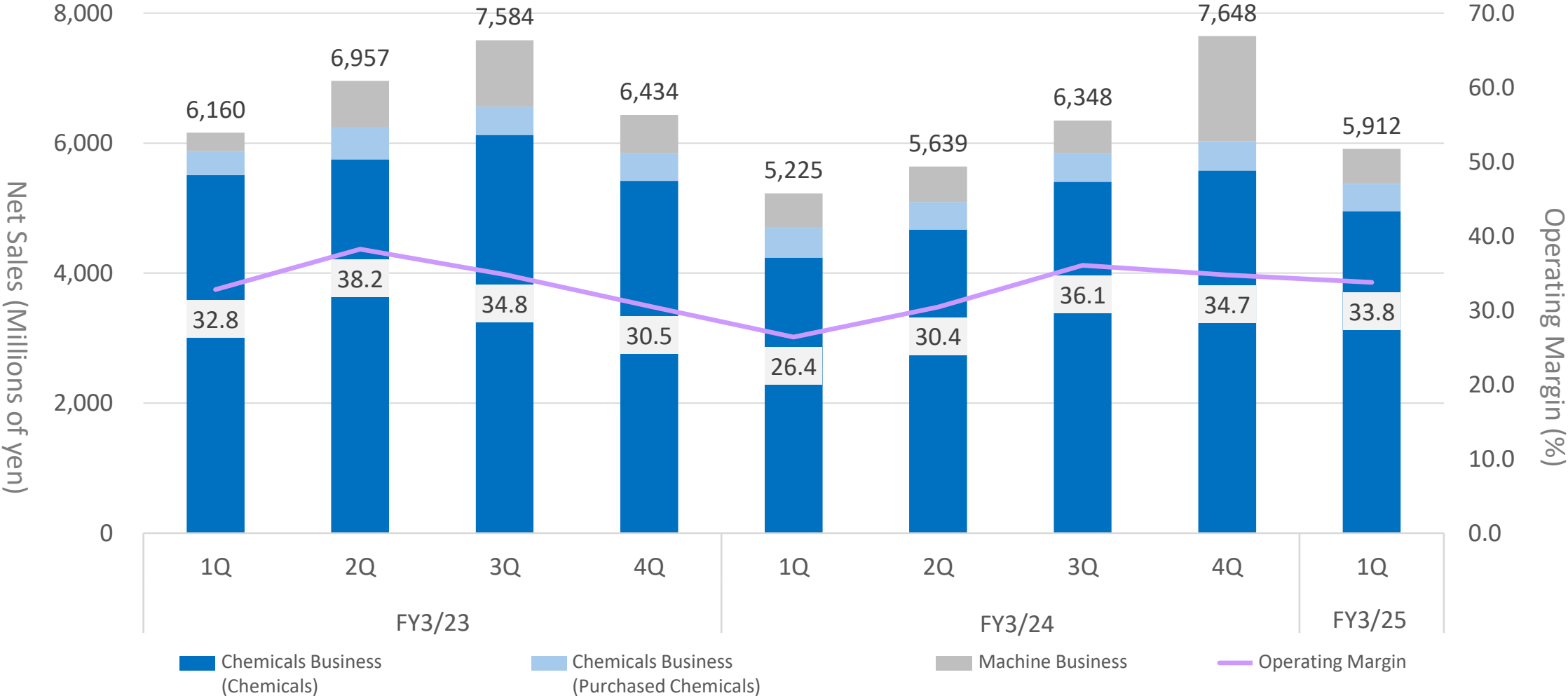
Changes in Consolidated Operating Profit for 1Q FY3/25



Quarterly Consolidated Financial Results



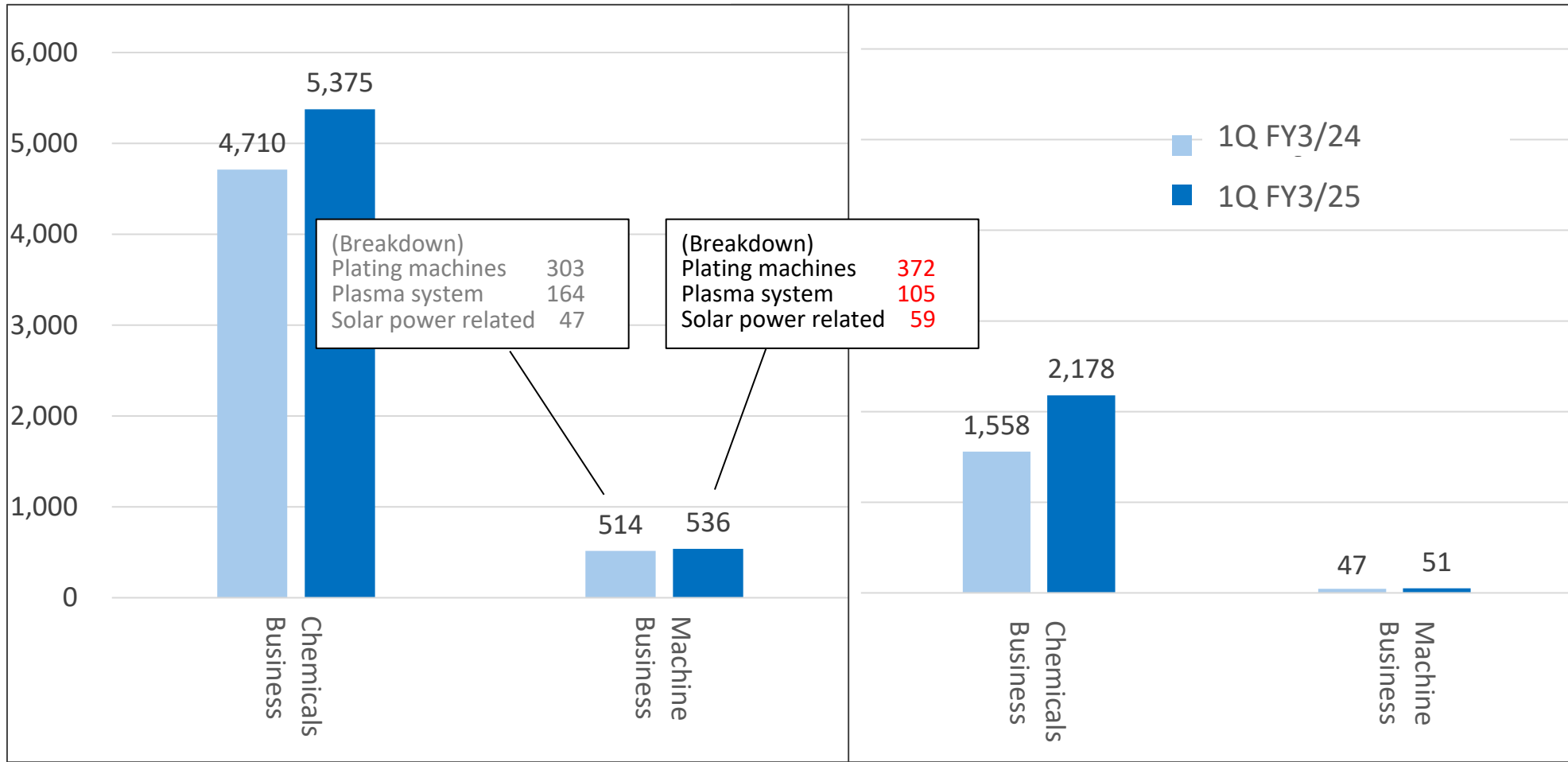
Quarterly Consolidated Financial Results (By Segment)



Consolidated Segment Results for 1Q FY3/25



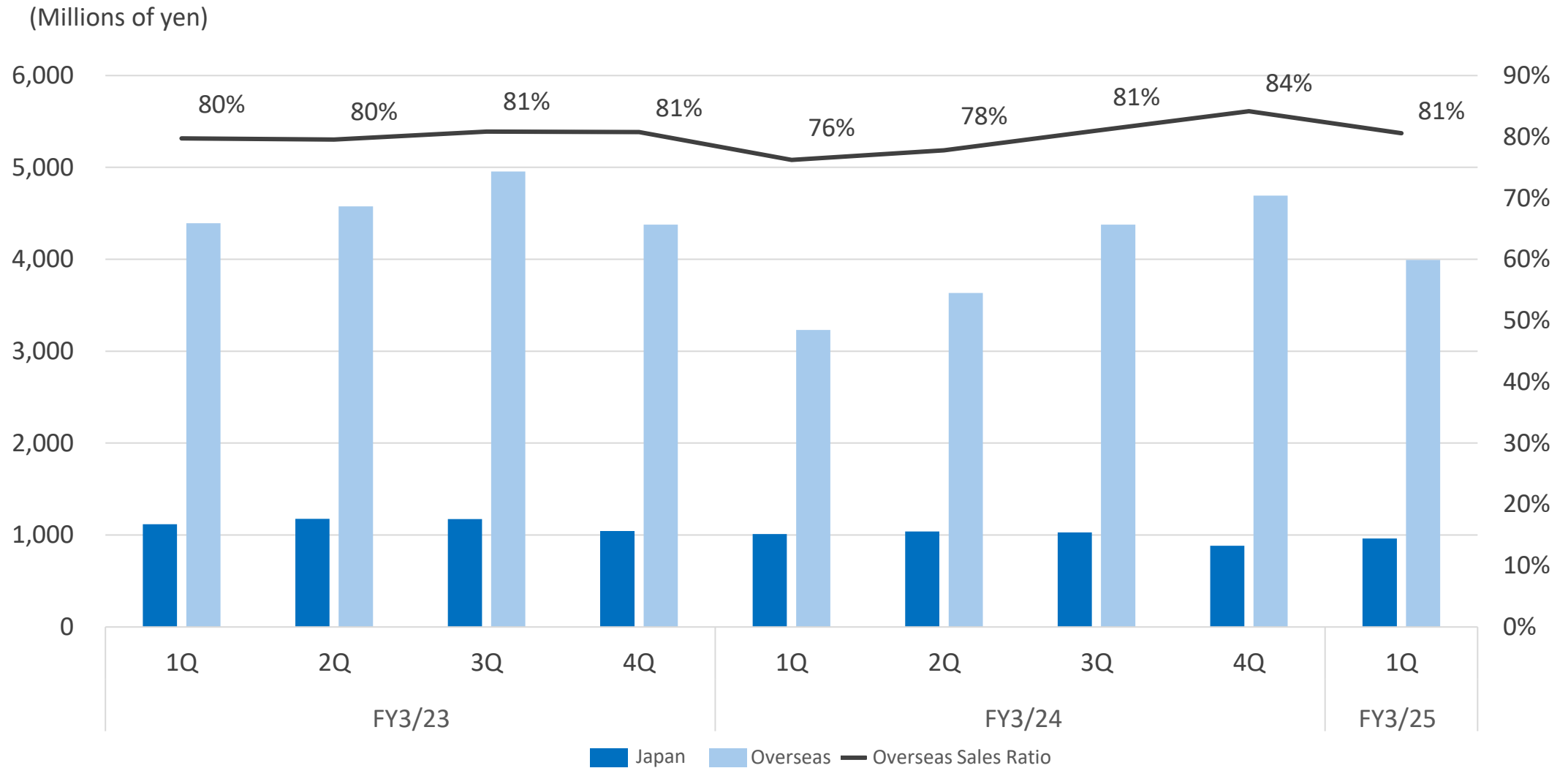
(Millions of yen)



Net Sales

Segment Profit (Loss)

Quarterly Sales of Chemicals in Japan and Overseas



Chemicals for POP, Via Filling and Etching | Quarterly Sales

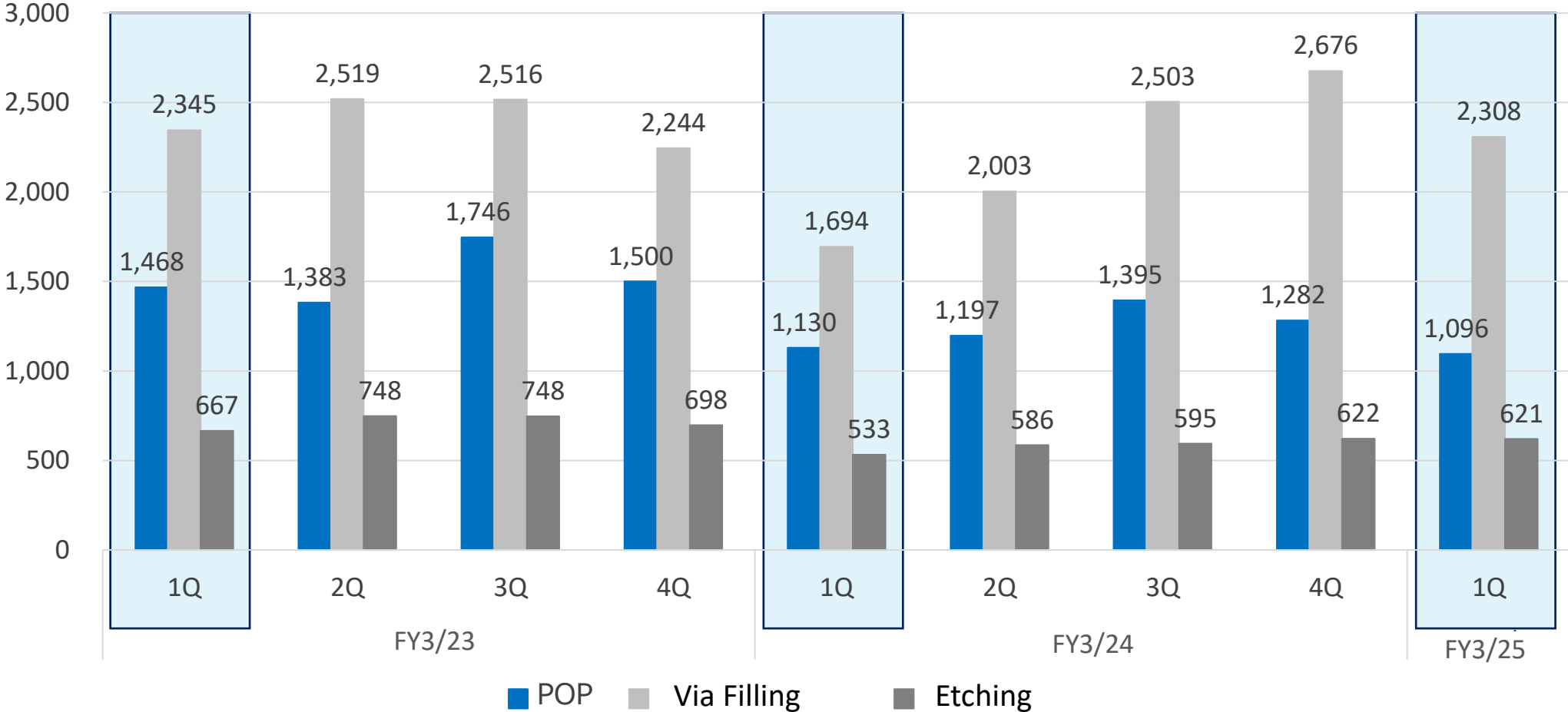


POP: Planting on Plastics, mainly for automotive components

Via Filling: Additive for copper plating for PWBs and semiconductor package substrates, mainly for smartphones and PCs

Etching: Additives for PWBs and semiconductor package substrates, mainly for PCs and communication ICs

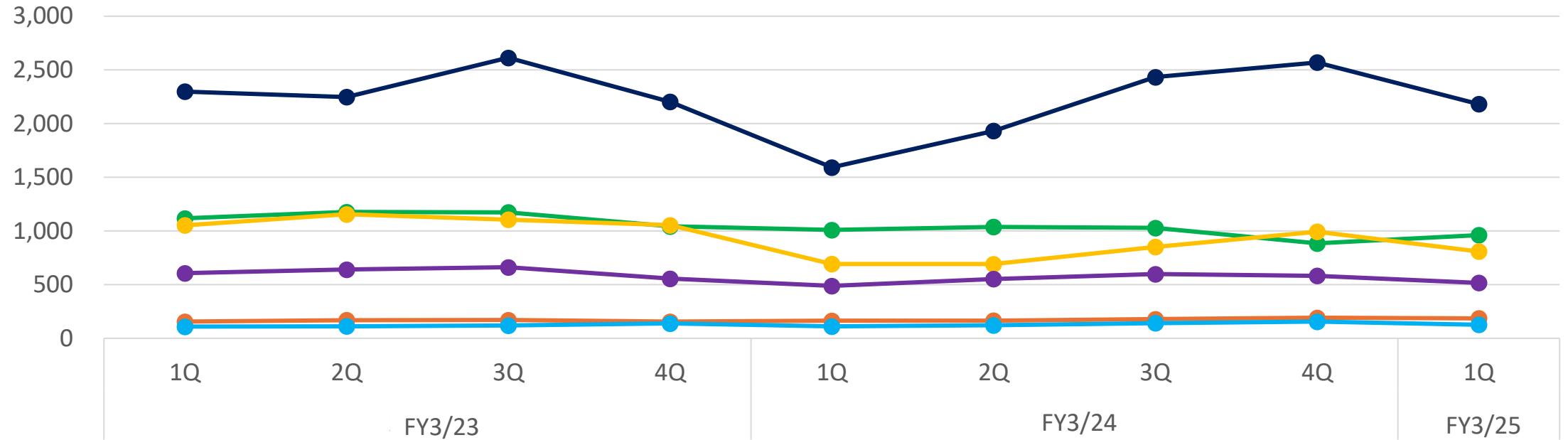
(Millions of yen)



Quarterly Sales of Chemicals by Region



(Millions of yen)



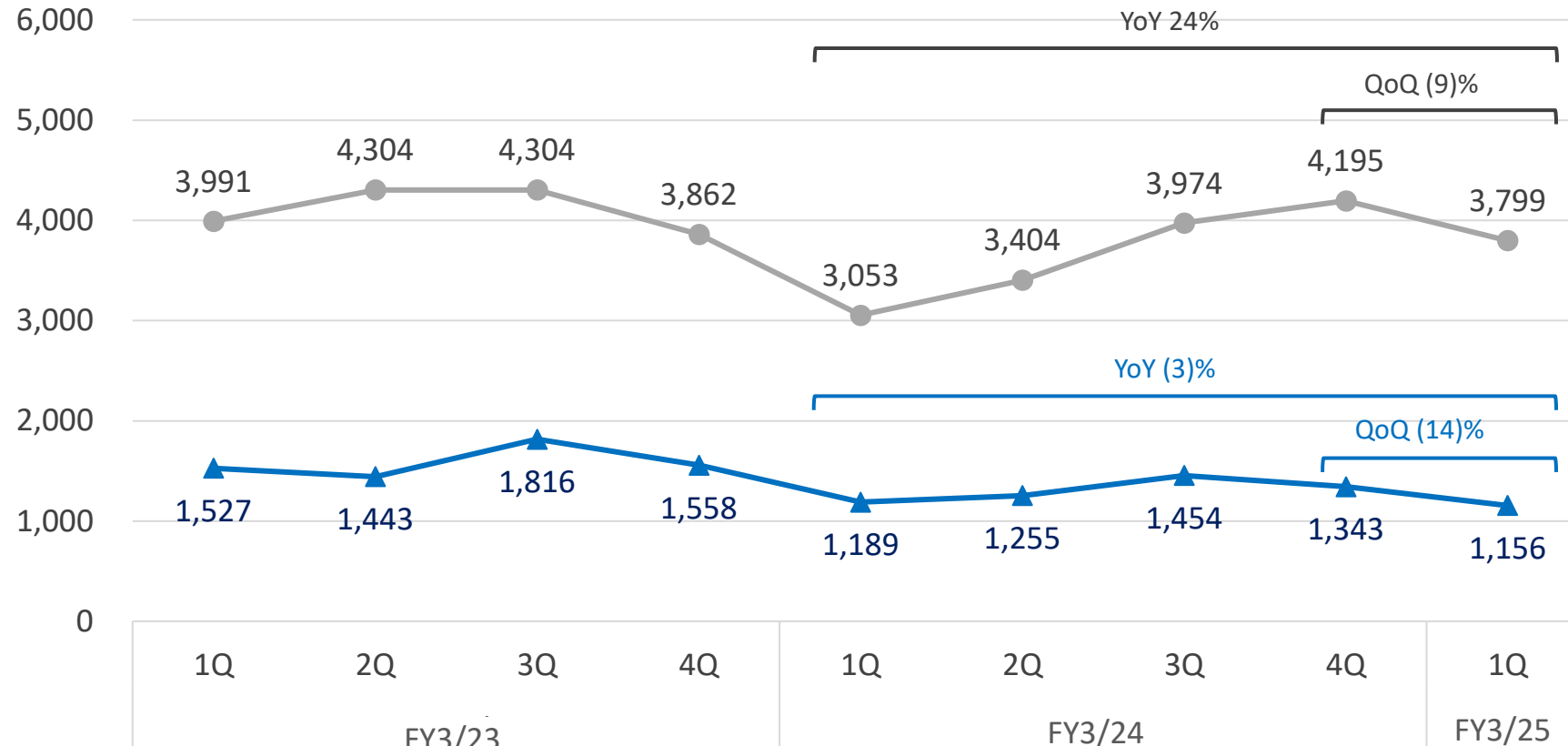
	FY3/23				FY3/24				FY3/25
	1Q	2Q	3Q	4Q	1Q	2Q	3Q	4Q	1Q
Japan	1,117	1,177	1,173	1,043	1,009	1,038	1,028	884	962
China	2,307	2,247	2,612	2,203	1,591	1,931	2,432	2,569	2,181
Taiwan	1,052	1,155	1,106	1,054	692	691	851	994	809
S. Korea	607	641	662	556	488	553	598	582	517
Thailand	156	170	170	155	164	166	179	191	186
Vietnam	109	112	120	139	111	121	142	156	127

Quarterly Sales of Chemicals by Category



Consolidated

(Millions of yen)



● Chemicals for Electronic Components
 ▲ Chemicals for Decoration and Function

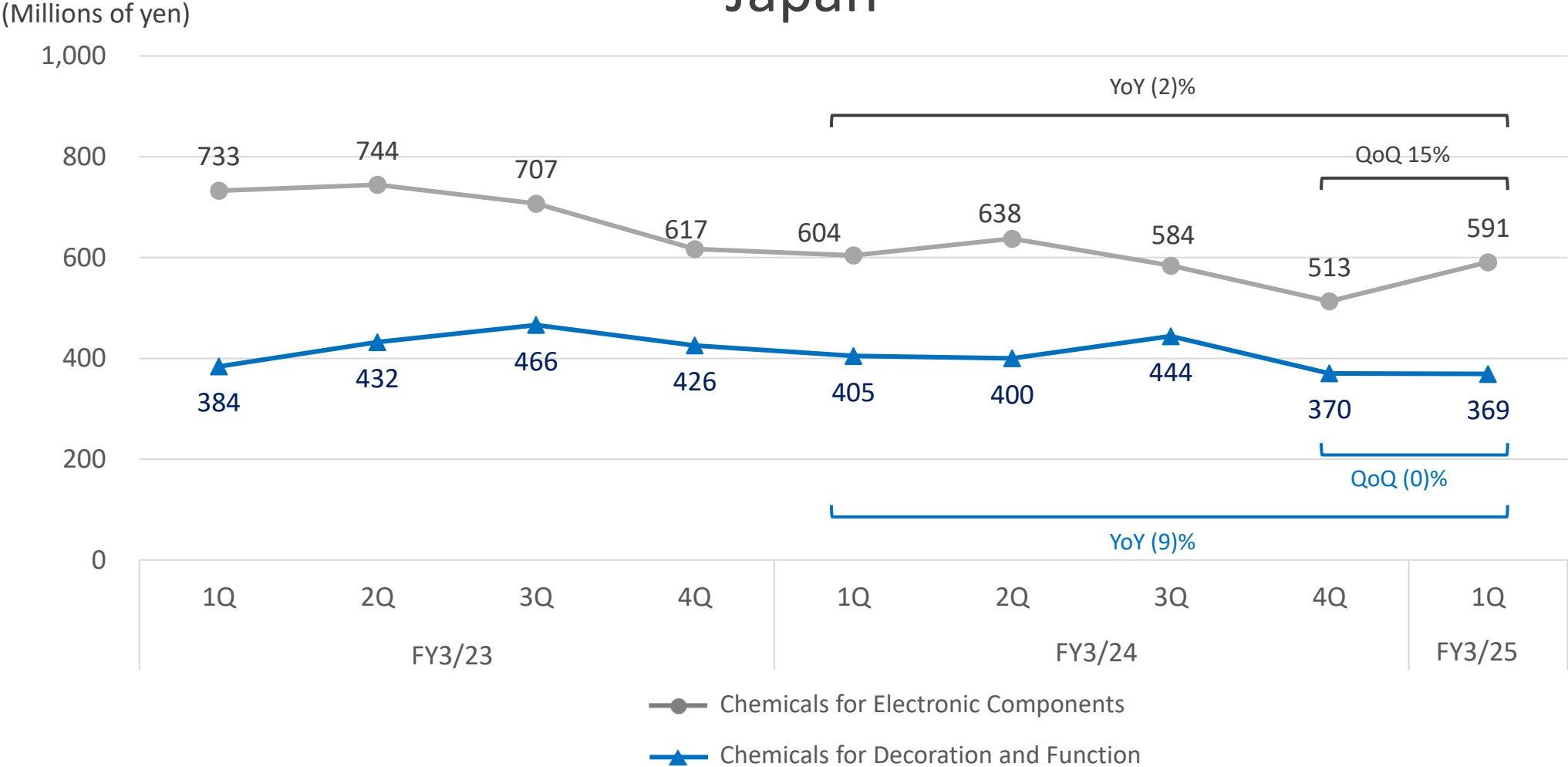
(Chemicals for Electronic Components)
 Core Products: Via filling
 PWBs, connectors, surface treatment
 (plating) chemicals for semiconductor
 sector

(Chemicals for Decoration and Function)
 Core Products: POP
 Chemicals for decoration and rust-
 proofing
 Surface treatment (plating) chemicals
 mainly for automotive components and
 water faucet clasps

Quarterly Sales of Chemicals by Region



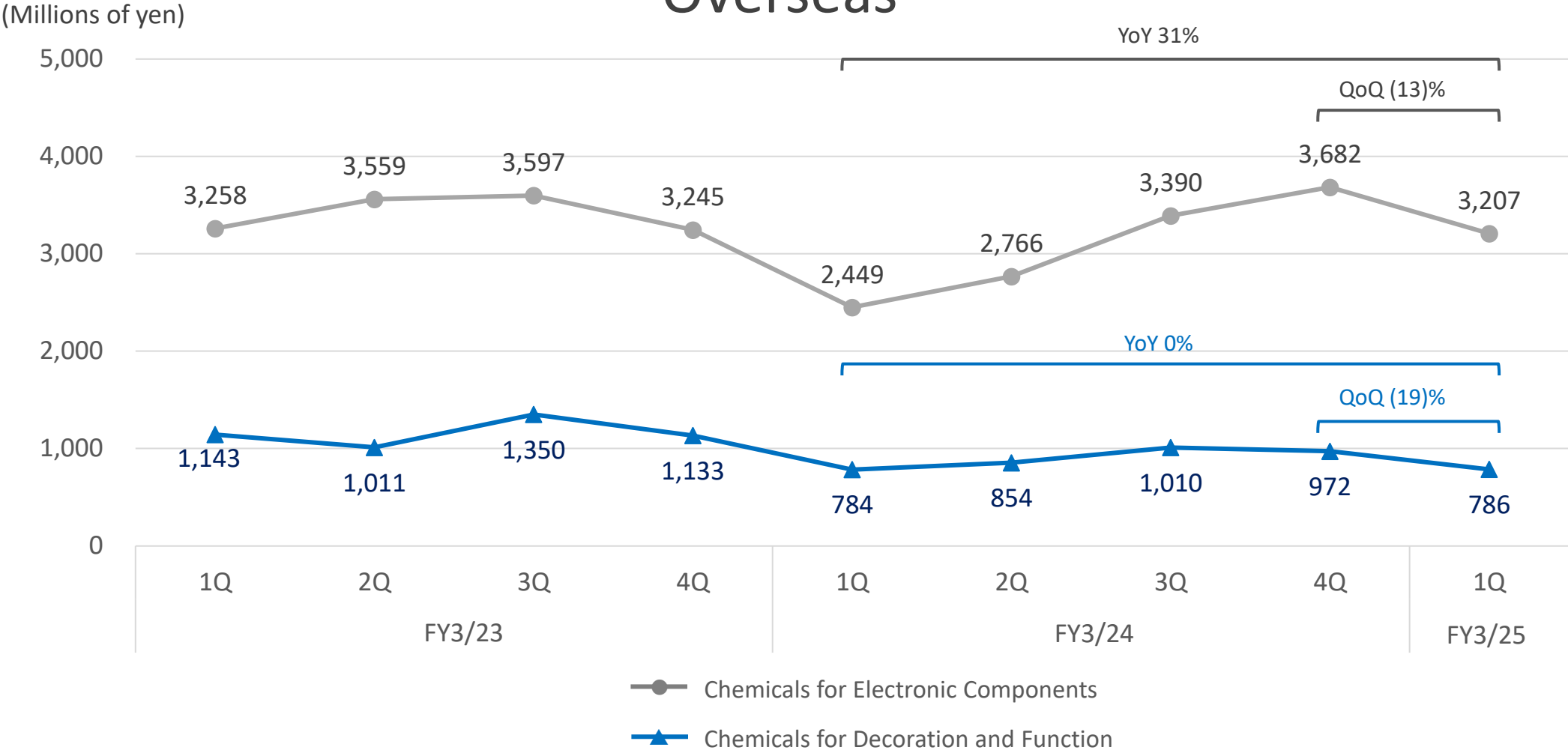
Japan



Quarterly Sales of Chemicals by Region



Overseas

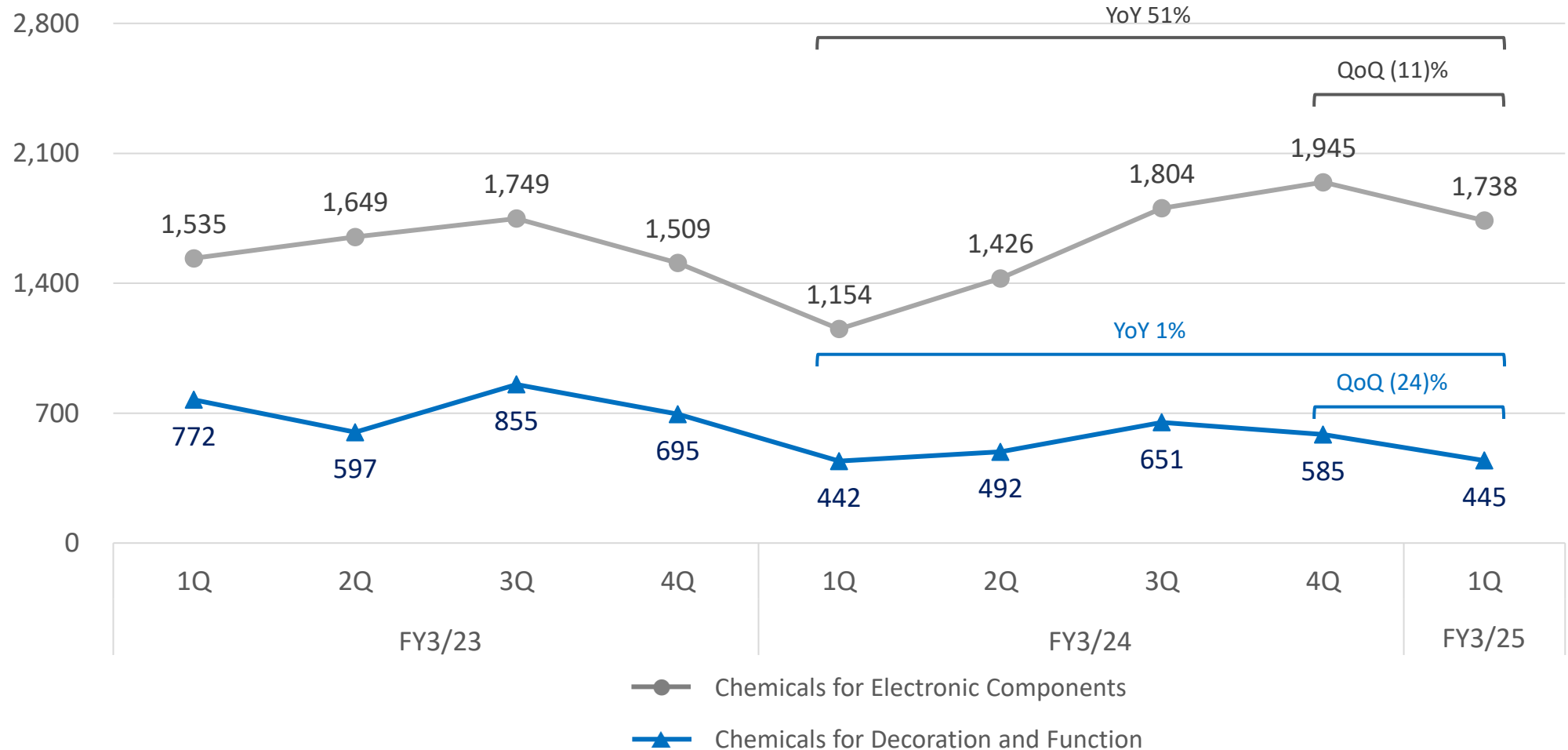


Quarterly Sales of Chemicals by Region



China

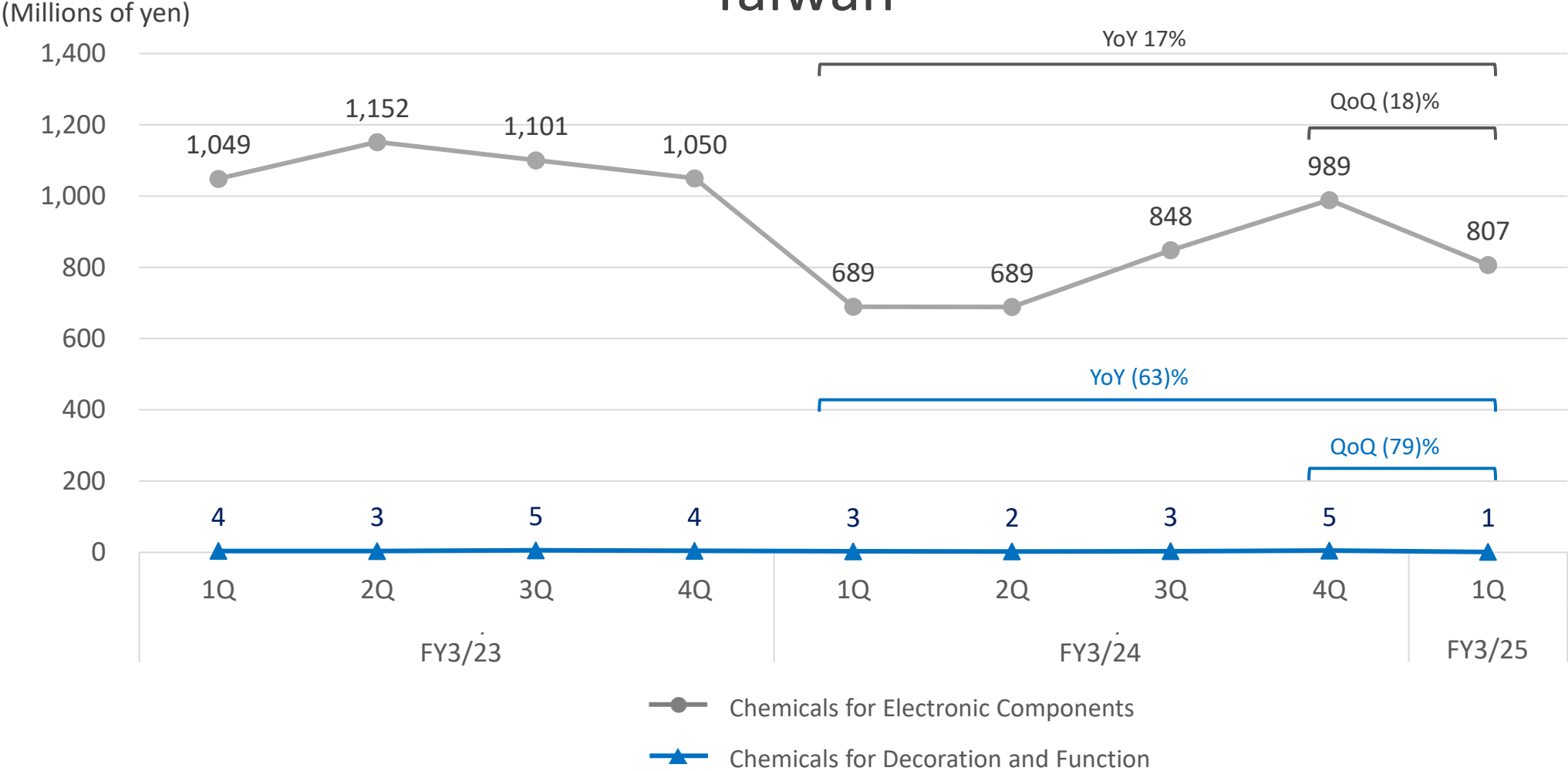
(Millions of yen)



Quarterly Sales of Chemicals by Region



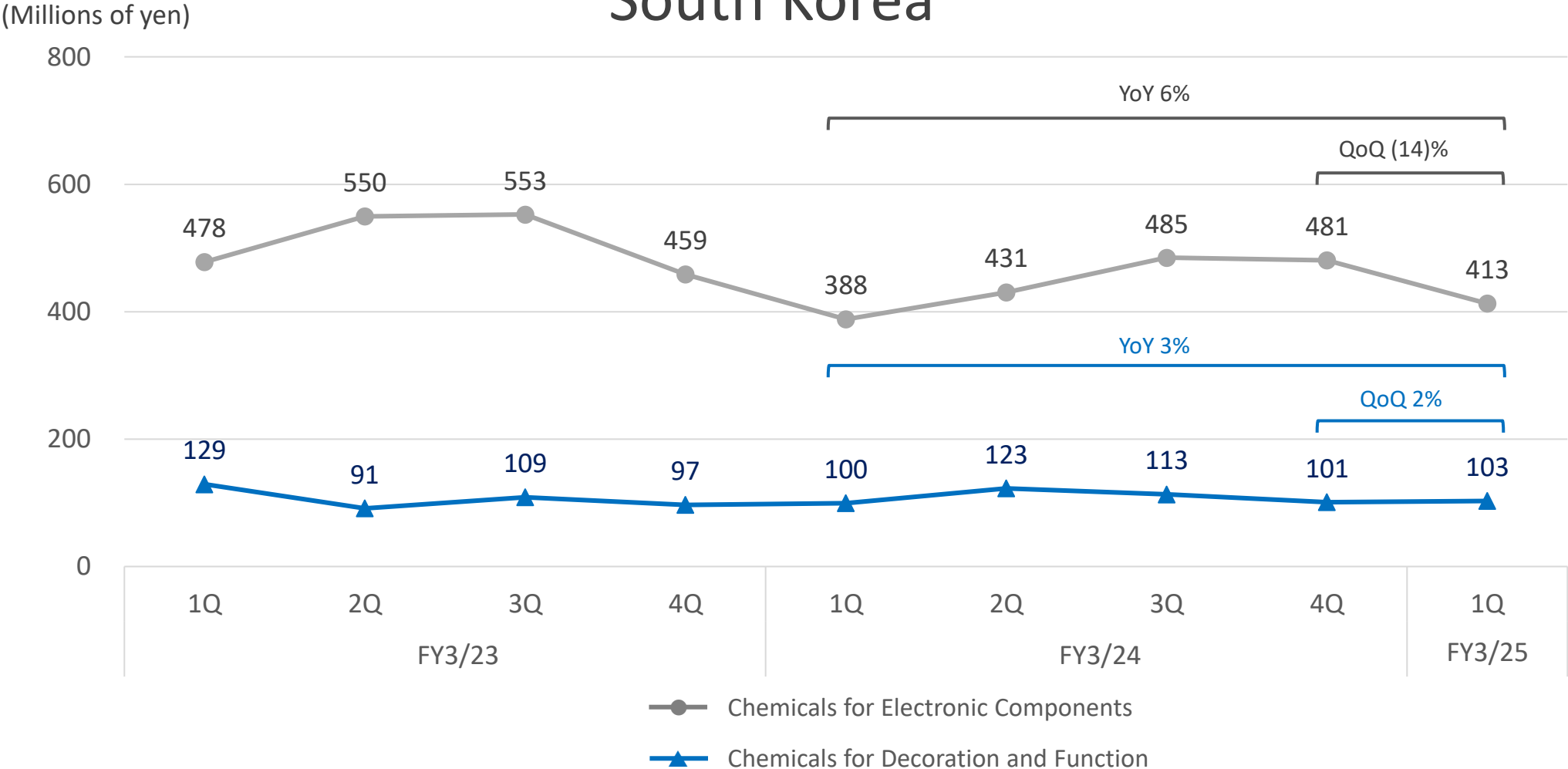
Taiwan



Quarterly Sales of Chemicals by Region



South Korea



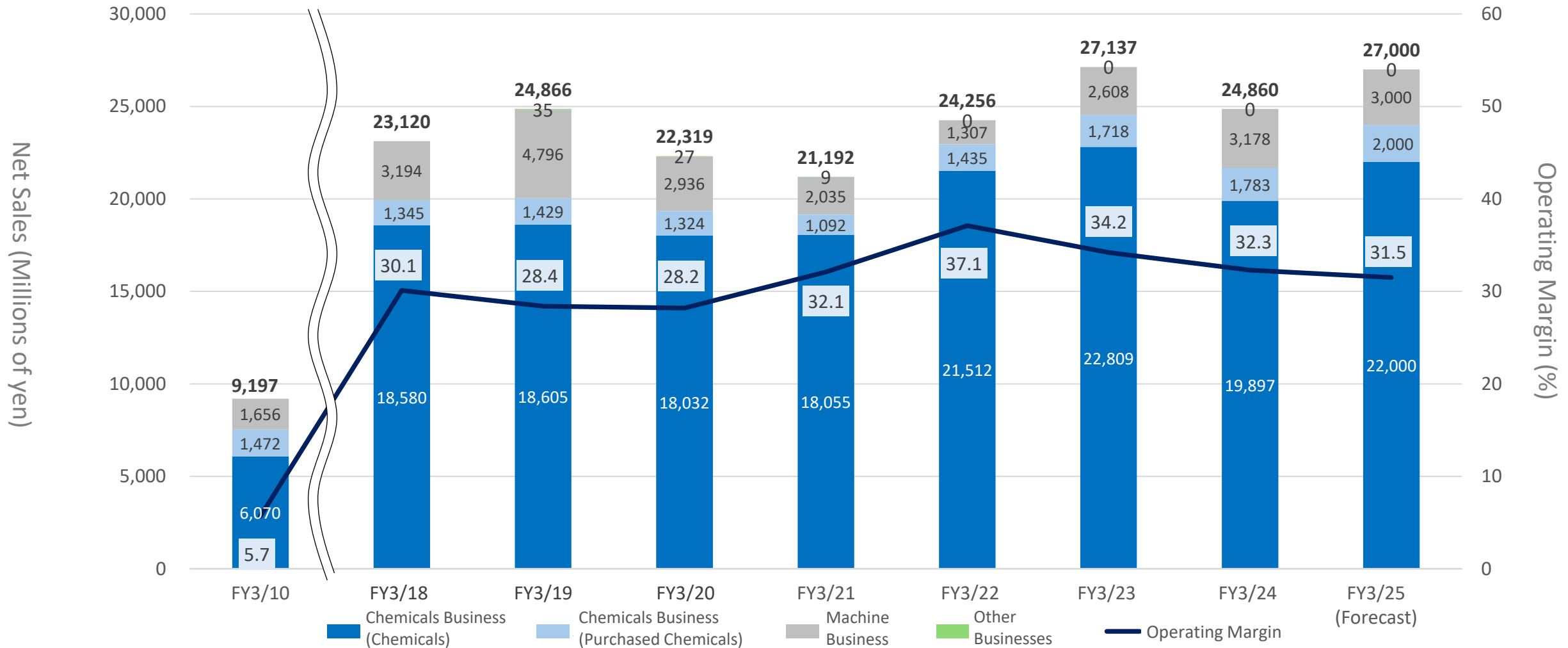
Forecasts for FY3/25



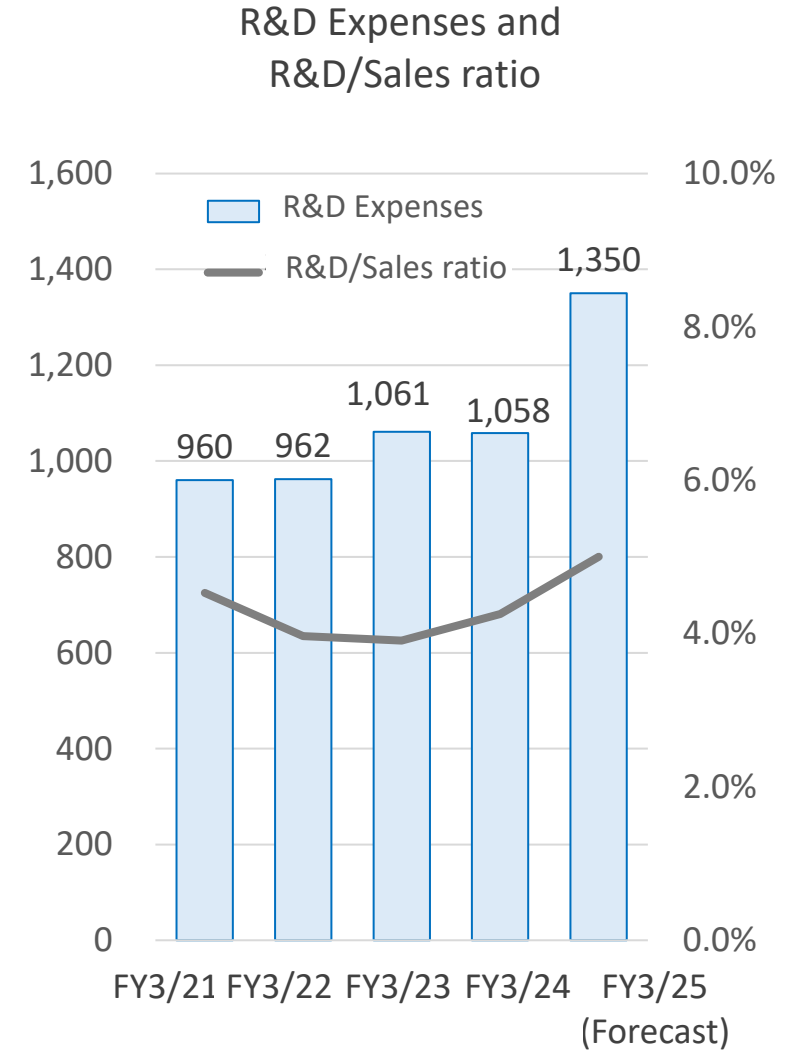
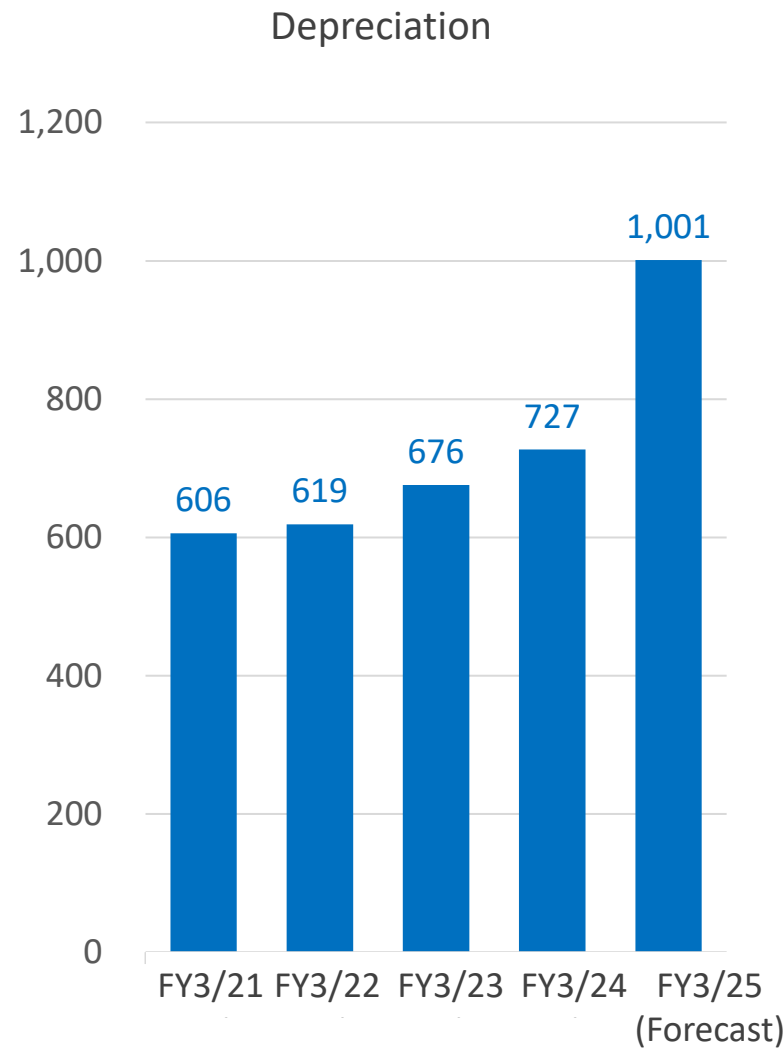
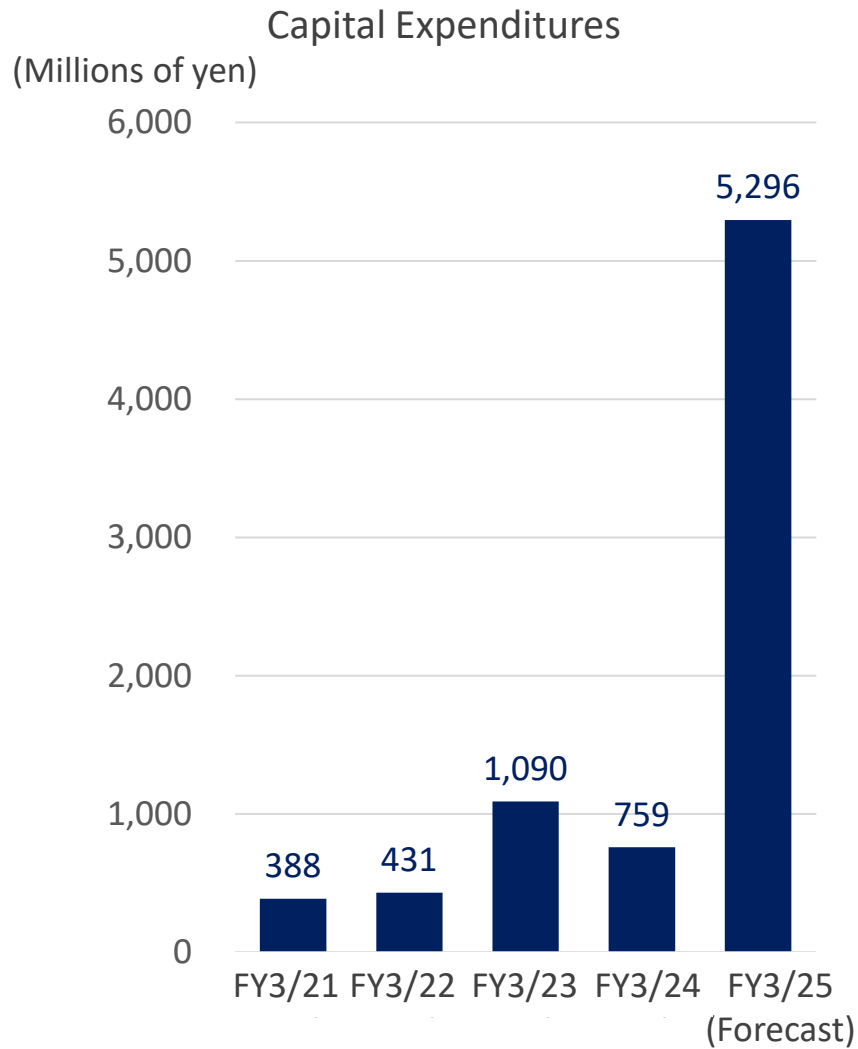
(Millions of yen)

FY3/25	1Q (Results)	1H (Forecasts)	Full year (Forecasts)	Progress rate against full- year forecast
Net sales	5,912	12,100	27,000	21.9%
Operating profit	1,995	3,870	8,500	23.5%
Ordinary profit	2,237	3,870	8,500	26.3%
Profit attributable to owners of parent	1,508	2,680	5,900	25.6%
Net income per share	59.55 yen	105.78 yen	232.86 yen	-

Annual Sales by Business (incl. Forecast)



Capital Expenditures, Depreciation and R&D Expenses



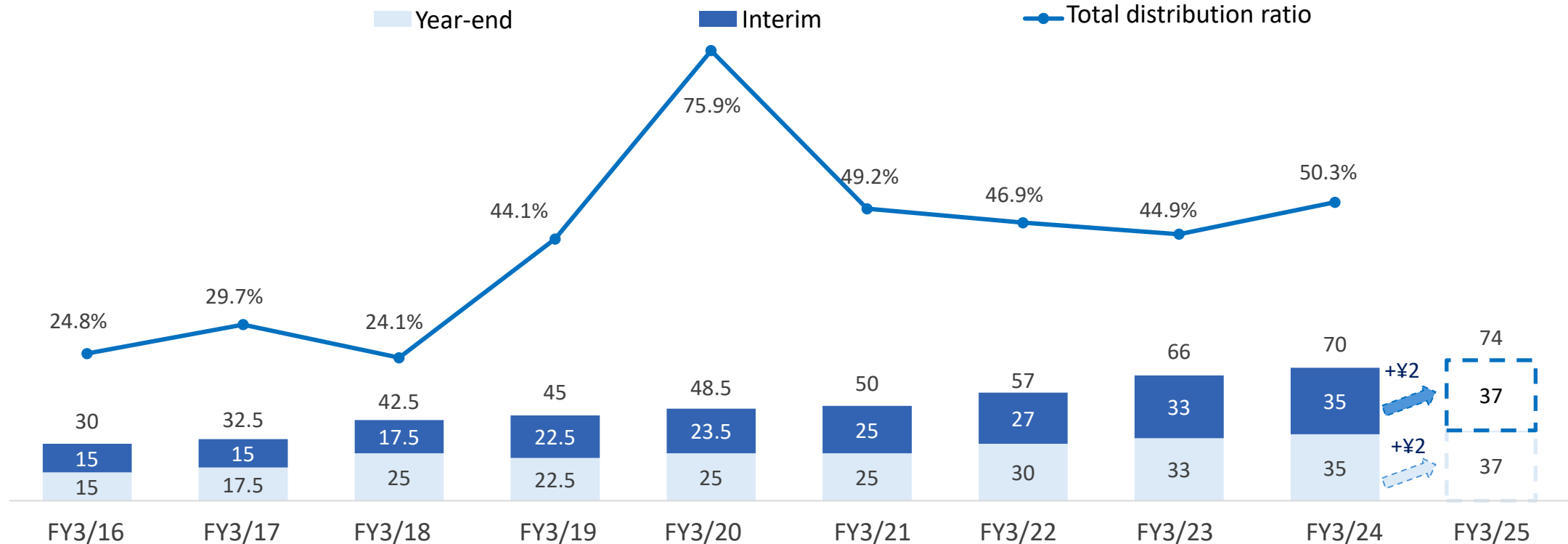
FY3/25 Equity Policy



Dividends per share
(Forecasts)

Interim dividend: 37 yen
Year-end dividend: 37 yen

Plans to increase dividends for
15 consecutive fiscal years



Basic
policy

- Continue to make investments for sustainable growth while securing liquidity on hand and maintaining stable financial base
- Continue a consistent dividend increase
- Return profits to shareholders through well-timed repurchases of stock with total distribution ratio of about 50%

Efforts in Addressing ESG Challenges



JCU aims to become a global company that continues to grow in a sustainable fashion by addressing ESG challenges through its business activities.

Environment



Development of environmentally responsible products

- Chromic acid-free etching process
- Eco-friendly chemical nickel plating process
- Eco-friendly decorative copper sulfate plating process



CO2 emissions (non-consolidated)

1,005 tons of CO₂ (as of end-March 2024)

* Down 30.6% from those in FY3/14



ESG external rating

CDP climate change 2023:
received a score of B



Social



Ratio of female managers (non-consolidated)

11.6% (as of end-March 2024)



ISO 9001 certified production sites in Japan and overseas

12 sites in 7 countries (as of end-March 2024)

* Japan, China, Taiwan, South Korea, Thailand, Vietnam, and Mexico

Governance



Corporate governance structure

- Number of Directors
Internal: 6, Outside: 3 (including 1 female)
- Number of Audit & Supervisory Board Members
Full-time: 1, Outside: 2 (including 1 female)

- Company Profile
- Surface Treatment Technology in Future
- Major Distribution Channels
- Major Products
- Usages of Chemicals and Typical Final Products

Company Profile



Founded in	:	December 1957
Established on	:	April 1, 1968
Capital stock	:	1,266 million yen
Annual sales	:	Non-consolidated: 13.8 billion yen / Consolidated: 24.8 billion yen (For the fiscal year ended March 31, 2024)
Head office	:	TIXTOWER UENO 16F, 8-1 Higashiueno 4-chome, Taito-ku, Tokyo
Lines of business	:	Manufacturing and sale of surface treatment chemicals, surface treatment machines, and related materials
Representative Directors	:	Masashi Kimura, Chairman and CEO Akihisa Omori, President and COO
Employees	:	Non-consolidated: 235 / Consolidated: 538 (As of March 31, 2024)

ISO Certificates

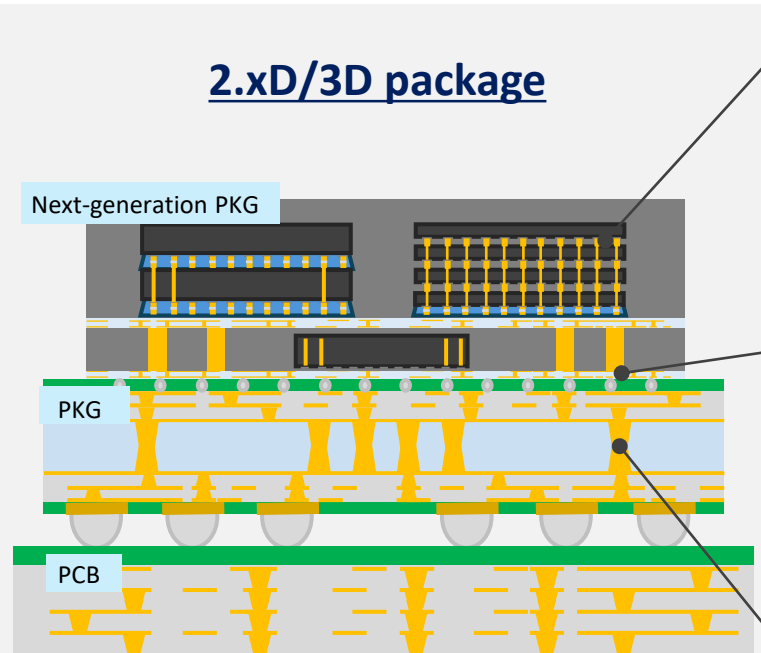
ISO9001	Production Headquarters, Head Office Sales and Marketing Department, and R&D Center (JCQA-0281)
ISO14001	Production Headquarters and R&D Center (JCQA-E-0143)

Surface Treatment Technology in Future —Electronic Components—

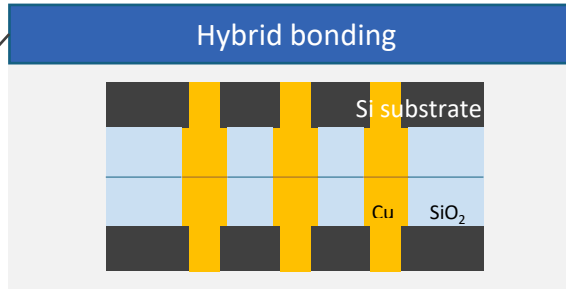
Target

Next-generation PKG boards for AI accelerators, data centers, high-performance electronic devices

Surface treatment technology in future



- Diversified packaging technology for high performance
- High-density mounting allows use of larger substrates
- Shorter connections between chips

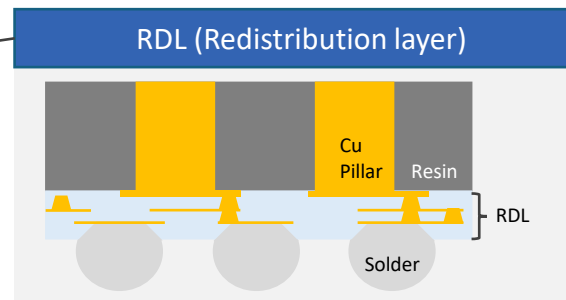


Expected primary application

Memory

Performance required by surface treatment technology

Higher reliability for connectivity
Outstanding electrical properties

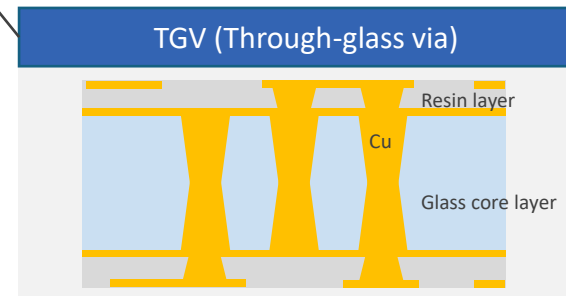


Expected primary application

FO-WLP / PLP
RDL interposers

Performance required by surface treatment technology

Improve within wafer non-uniformity
Improve via filling for thin-film layer



Expected primary application

Glass core substrates (FC-BGA)
Glass interposers

Performance required by surface treatment technology

Void free
Improve via filling for thin-film layer

Surface Treatment Technology in Future — Decoration & Function—

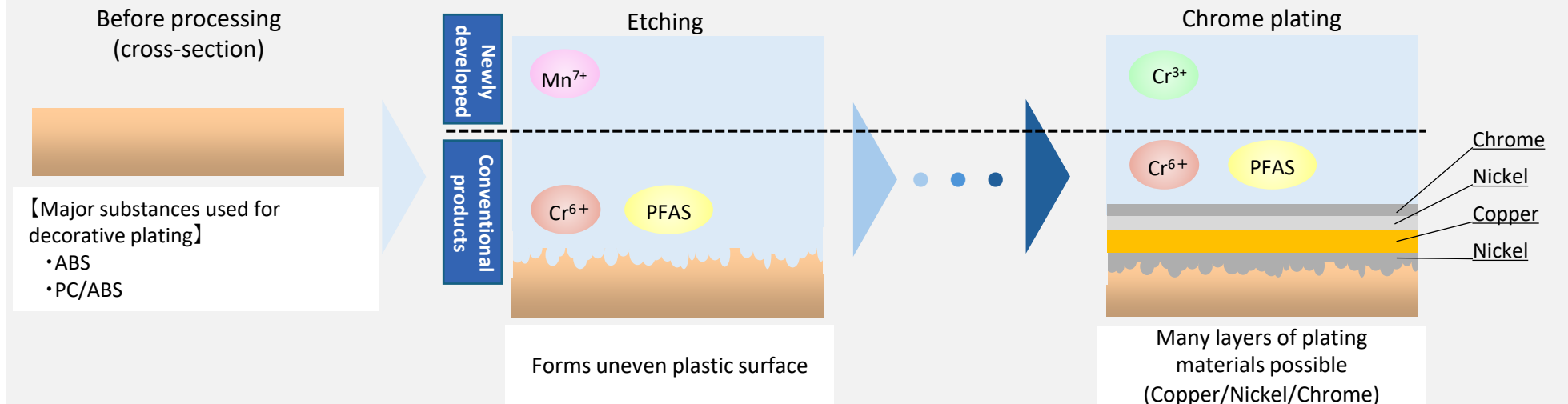
Target

Automotive components (front grilles, door handles, emblems, etc.)
Faucet parts (showerheads, drain plugs, etc.)

Surface treatment technology in future

Environmentally friendly surface treatment technology

Plating technology with no hexavalent chromium (Cr^{6+}) and no PFAS



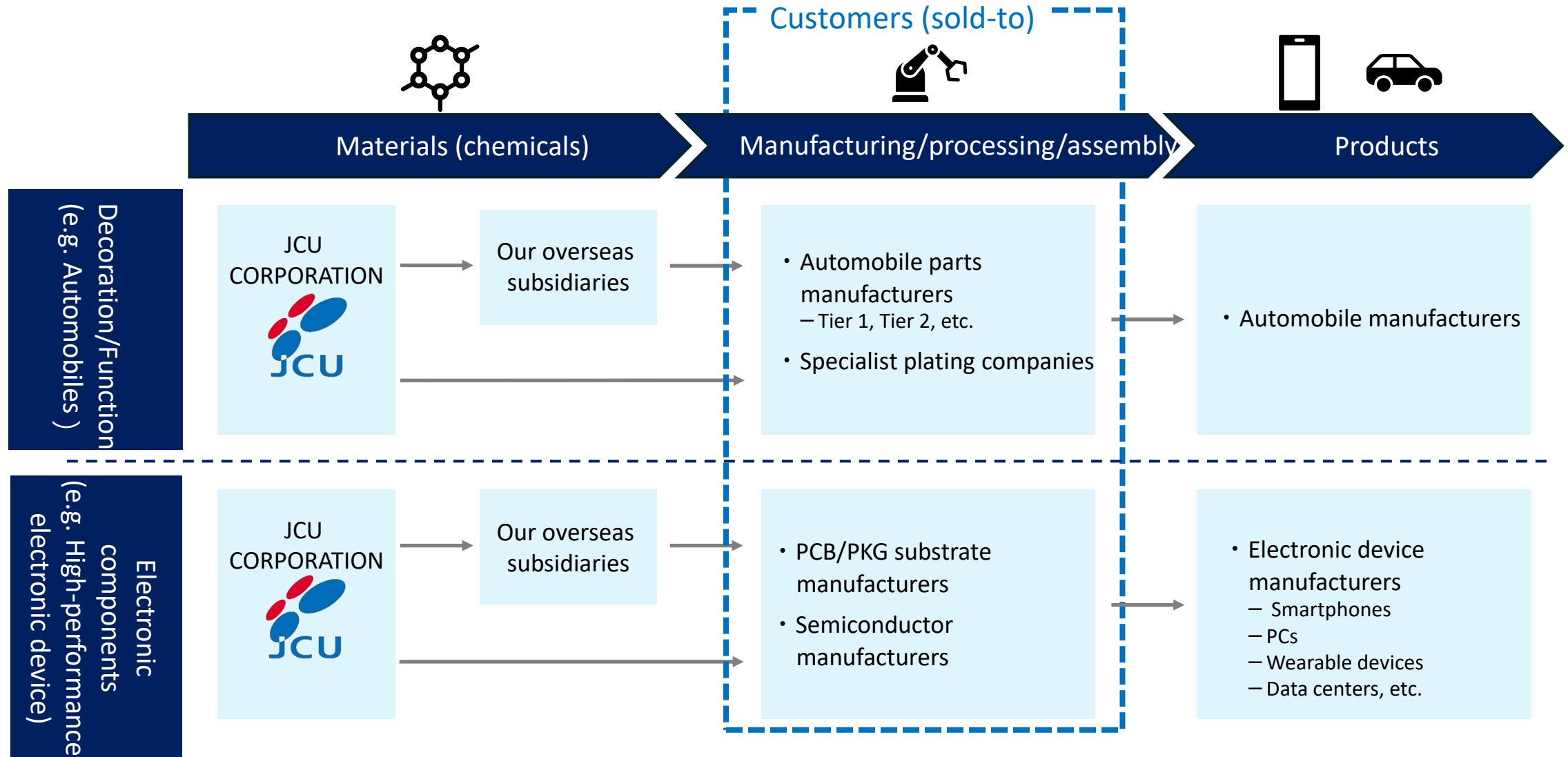
○ Conventional process

Uses environmentally harmful Cr^{6+} and PFAS in the first and last processes of decorative plating on plastic

○ Environmentally friendly process created by JCU

A comprehensive process with a low environmental impact due to the elimination of Cr^{6+} and PFAS from all processes

Major Distribution Channels



Major Products

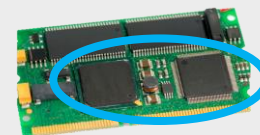


Chemicals Business	For decoration and function	Automotive parts (front grilles, door handles, emblems, etc.) Faucet parts (water supply equipment, showerheads, drain plugs, etc.) Construction materials (bolts, nuts, etc.)
	For electronic components	PWBs (reversible and multilayer, build-up substrates, package substrates, etc.) Electronic components (lead frames, chip components, connectors, etc.) Semiconductors (silicon wafers)
Machine Business	Fully-automated surface treatment equipment	Fully-automated equipment from input of materials to completion of the plating process
	Peripheral equipment	Manufacturing and sale of filtration machines and other peripheral equipment to be attached to surface treatment equipment
	Automatic analytical control systems	Automatic management of plating solutions by analyzing concentrations of chemicals and adding chemicals when an insufficient level is detected
	Plasma system	Etching and washing devices for PWBs as part of pre-plating processes

Usages of Chemicals and Typical Final Products



Description of term		Final products
Chemicals for function/decoration	Surface treatment (plating) chemicals for decorative and rust-proofing purposes such as those for providing a metal appearance and preventing rust.	Automotive parts, faucet parts and construction materials
POP (Plating on Plastics) chemicals	Major products for chemicals for function/decoration Chemicals for metal coating on plastics	(Automotive parts) Front grilles, emblems, etc. (Faucet parts) Showerheads, water faucet cocks, etc.
Other	Chemicals for metal coating on metallic materials such as copper and steel	(Construction materials) Screws, hinges, etc.
Chemicals for electronic components	Plating chemicals for manufacturing PWBs, such as a circuit for electronic signals and an electrical contact for electronic components	5G-related components, data centers and other infrastructures and high-performance electronic devices
Via filling chemicals (for PCB/motherboards)	Copper plating chemicals for formulating interconnection onto PCB/motherboards	(5G-related components) 5G base stations, in-vehicle PWBs, smart home appliances, etc.
Via filling chemicals (for semiconductor package boards)	Copper plating chemicals for formulating interconnection onto semiconductor packages boards *Semiconductor packages boards: Circuit board for protecting a semiconductor chip from the external environment and mounting to PCB/motherboards	(Data centers and other infrastructures) Motherboards for communication servers etc.
Other	Plating chemicals for connectors and lead frames, etching chemicals for scraping unnecessary copper when formulating interconnection onto motherboards or semiconductor packages boards	(High-performance electronic devices) Smartphones, PCs, tablets, game consoles, etc.



This material contains current plans and forecasts of future performance of JCU CORPORATION. These plans and forecast figures are prepared by the Company based on currently available information. This material does not give any assurance or guarantee of the Company's future financial performance and actual results may differ substantially from these plans for a number of conditions or developments in the future.

JCU CORPORATION's website
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